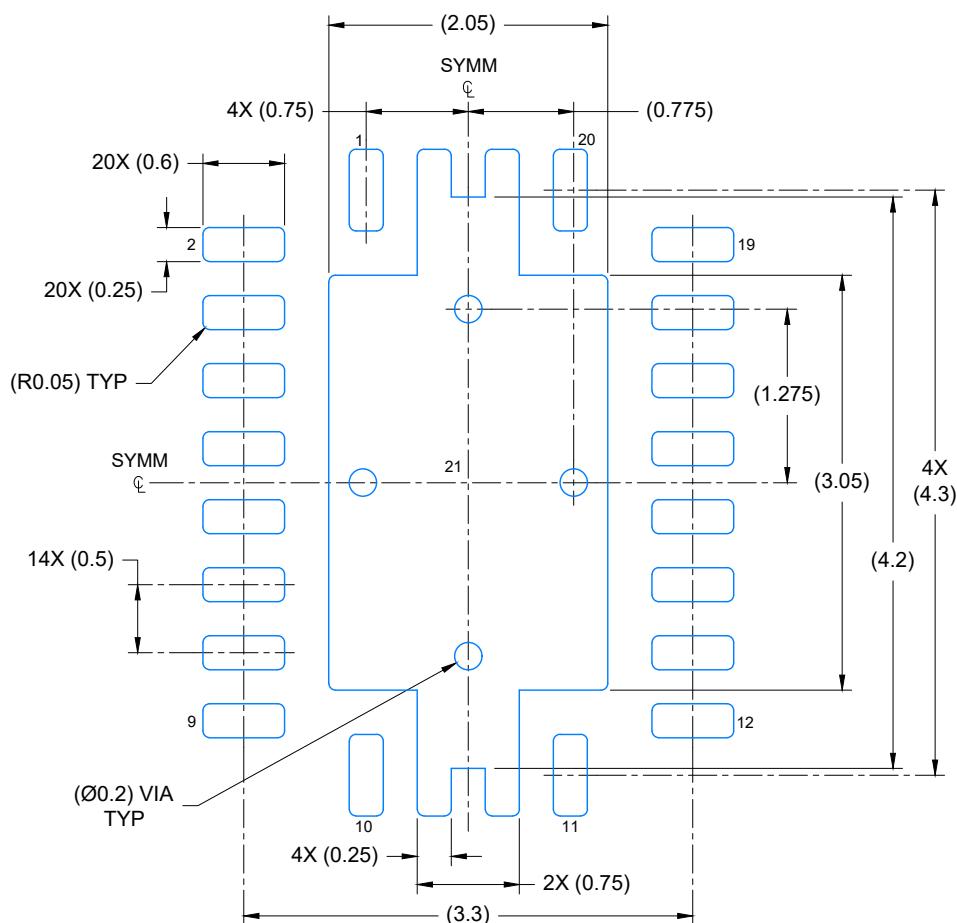


EXAMPLE BOARD LAYOUT

VQFN - 1 mm max height

RGY0020D

PLASTIC QUAD FLATPACK- NO LEAD



LAND PATTERN EXAMPLE

EXPOSED METAL SHOWN

SCALE: 18X



SOLDER MASK DETAILS

4225702/A 03/2020

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.